

DECLARATION FOR PATENT APPLICATION			AITY DOCKET NO. _____													
<p style="text-align: center;">As a below-named inventor, I hereby declare that</p> <p>My residence, post office address and citizenship are as stated below next to my name.</p> <p>I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter that is claimed and for which a patent is sought on the invention entitled: MULTI-LEVEL CIRCUIT SUBSTRATE, METHOD FOR MANUFACTURING SAME AND METHOD FOR ADJUSTING A CHARACTERISTIC IMPEDANCE THEREFOR</p> <p>the specification of which: (check one)</p>																
<input checked="" type="checkbox"/> is attached hereto																
was filed on _____ 19____, as U.S. or PCT International Application No. _____, and was amended on _____ 19____ (if applicable)																
<p>I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.</p> <p>I acknowledge the duty to disclose information that is material to patentability as defined in 37 CFR § 1.56.</p>																
<p>I hereby claim foreign priority benefits under 35 U.S.C. § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or under § 365(a) of any PCT international application which designated at least one country other than the United States of America, listed below, and have also identified below, by checking the "No" box, any foreign application for patent or inventor's certificate or any PCT international application having a filing date before that of the application on which priority is claimed.</p> <p style="text-align: right;">Priority Claimed:</p>																
Foreign (or PCT International) Application No.	Country	Foreign (or PCT International) Filing Date	Yes	No												
P 10-295132	Japan	October 16, 1998	X													
P 11-282505	Japan	October 4, 1999	X													
<p>The following foreign application(s), if any, were filed more than 12 months (6 months for designs) before this U.S. application:</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">Foreign Application No.</th> <th style="width: 30%;">Country</th> <th style="width: 20%;">Foreign Filing Date</th> </tr> </thead> <tbody> <tr><td> </td><td> </td><td> </td></tr> <tr><td> </td><td> </td><td> </td></tr> <tr><td> </td><td> </td><td> </td></tr> </tbody> </table>					Foreign Application No.	Country	Foreign Filing Date									
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<p>I hereby claim the benefit under 35 U.S.C. § 119(e) of any U.S. provisional application(s) that may be listed below.</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 60%;">U.S. Provisional Application No.</th> <th style="width: 40%;">Filing Date</th> </tr> </thead> <tbody> <tr><td> </td><td> </td></tr> <tr><td> </td><td> </td></tr> </tbody> </table>					U.S. Provisional Application No.	Filing Date										
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<p>I hereby claim the benefit under 35 U.S.C. § 120 of any United States application(s) or under § 365(c) of any PCT international application(s) designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior U.S. or PCT international application in the manner provided by 35 U.S.C. § 112, ¶ 1, I acknowledge the duty to disclose information that is material to patentability as defined in 37 CFR § 1.56 that became available between the filing date of the prior application and the national or PCT international filing date of this application.</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 30%;">U.S. (or PCT) Parent Application No.</th> <th style="width: 30%;">U.S. (or PCT) Parent Filing Date</th> <th style="width: 40%;">Status (patented, pending, abandoned)</th> </tr> </thead> <tbody> <tr><td> </td><td> </td><td> </td></tr> <tr><td> </td><td> </td><td> </td></tr> </tbody> </table>					U.S. (or PCT) Parent Application No.	U.S. (or PCT) Parent Filing Date	Status (patented, pending, abandoned)									
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<p>I hereby appoint the practitioners associated with CUSTOMER NUMBER 20,121 as having Power of Attorney to prosecute this application and transact all related business before the USPTO, and I direct that all correspondence be sent to the address associated with that Customer Number.</p> <p>Direct Telephone Calls to: _____ Voice: (202) 508-4000 Thelen Reid & Priest FAX: (202) 508-4321 FAX: (202) 508-4395 for patent & trademark matters only</p>																
<p>I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.</p>																

Full name of sole or first inventor	Hideki IWAKI		
Inventor's Signature:	✓ <i>Hideki Iwaki</i>	Date:	✓ October 1, 1999.
Residence Address:	Osaka, Japan		
Country of Citizenship:	Japan		
Post Office Address:	4-5, Hoshimicho, Ibaraki-shi, Osaka 567-0843		

JAPAN

Additional inventors are named on attached supplemental sheet(s).

DECLARATION FOR PATENT APPLICATION

PAGE TWO

Full name of second inventor:	Yutaka TAGUCHI	
Inventor's Signature:	✓ <i>Yutaka Taguchi</i>	Date: ✓ October 1, 1999.
Residence Address:	Osaka, Japan	
Country of Citizenship:	Japan	
Post Office Address:	33-3, Nishimachi, Takatsuki-shi, Osaka 569-0854 JAPAN	

Full name of third inventor:	Tetsuyoshi OGURA	
Inventor's Signature:	✓ <i>Tetsuyoshi Ogura</i>	Date: ✓ October 1, 1999.
Residence Address:	Osaka, Japan	
Country of Citizenship:	Japan	
Post Office Address:	14-25-101, Hitotsuya 1-chome, Settsu-shi, Osaka 566-0043 JAPAN	

Full name of fourth inventor:		
Inventor's Signature:	✓	Date: ✓
Residence Address:		
Country of Citizenship:		
Post Office Address:		

Full name of fifth inventor:		
Inventor's Signature:	✓	Date: ✓
Residence Address:		
Country of Citizenship:		
Post Office Address:		

Full name of sixth inventor:		
Inventor's Signature:	✓	Date: ✓
Residence Address:		
Country of Citizenship:		
Post Office Address:		

Full name of seventh inventor:		
Inventor's Signature:	✓	Date: ✓
Residence Address:		
Country of Citizenship:		
Post Office Address:		

ASSIGNMENT OF UNITED STATES APPLICATION FOR PATENT

Whereas the undersigned, (1) Hideki IWAKI, (2) Yutaka TAGUCHI,
(3) Tetsuyoshi OGURA, have invented certain
improvements in MULTI-LEVEL CIRCUIT SUBSTRATE, METHOD FOR MANUFACTURING SAME
ID METHOD FOR ADJUSTING A CHARACTERISTIC for which an application for Letters
Patent of the United States of America: IMPEDANCE THEREFOR

<input type="checkbox"/>	was executed on even date herewith
<input type="checkbox"/>	was filed on _____ and was assigned Application No. _____

Matsushita Electric

Whereas, Industrial Co., Ltd., (hereinafter referred to as Assignee) a
corporation of _____ and having an address 1006, Oaza Kadoma, Kadoma-shi,
OSAKA 571-8501 JAPAN, is desirous of acquiring an interest therein and in the Letters
Patent to be obtained therefor:

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and other good and valuable
consideration, the receipt of which is hereby acknowledged, the undersigned by these presents,
hereby assign, sell and transfer unto the said Assignee, for the territory of the United States of
America and throughout the world, all right, title and interest in and to said invention and
application, and any and all divisions or continuations thereof, and in and to any Letters Patent
that may be granted therefor together with any reissues, extensions or renewals thereof, the same
to be held and enjoyed by the Assignee for Assignee's own use and behoof, and for Assignee's
legal representatives, successors and assigns, to the full end of the term for which said Letters
Patent may be granted, as fully and entirely as the same would have been held by the undersigned
had this Assignment and same not been made; and the undersigned, and legal representatives
thereof, hereby covenant and agree to execute and deliver any and all papers, and do all lawful
acts that said Assignee may consider necessary or advisable to perfect title to said invention and
to obtain Letters Patent therefor, and any divisions, continuations, reissues, extensions and
renewals thereof, and agree at any time upon request, to communicate to said Assignee,
Assignee's successors and assigns, such facts relating to said invention and Letters Patent or the
history thereof as may be known to the undersigned and testify as to the same in any interferences,
opposition or other litigation, when requested to do so, all without further consideration than that
now paid, but at the expense of the said Assignee, Assignee's successors or assigns.

We authorize our attorneys at THELEN REID & PRIEST L.L.P. to insert herein any
identifying information concerning this patent application, such as its title, filing date and
application number.

<u>Hideki Iwaki</u>	<u>October 1, 1999.</u>
First Inventor	Date
<u>Yutaka Taguchi</u>	<u>October 1, 1999.</u>
Second Inventor	Date
<u>Tetsuyoshi Ogura</u>	<u>October 1, 1999.</u>
Third Inventor	Date

THELEN REID & PRIEST L.L.P.

701 Pennsylvania Avenue NW Washington, D.C. 20004 (202) 508-4000